

# H263-S67-AAW1

High Density Server - 2U 4-Node DP 8-Bay NVMe/SATA

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## Key Features

- 2U 4-node rear access server system
- Dual 5th/4th Gen Intel® Xeon® Scalable Processors per node
- 8-Channel DDR5 RDIMM, 64 x DIMMs
- Dual ROM Architecture
- 1 x CMC port
- 8 x 2.5" Gen5 NVMe/SATA/SAS-4 hot-swappable bays
- 4 x M.2 slots with PCIe Gen4 x4 interface (optional)
- 4 x LP PCIe Gen5 x16 slots
- 4 x OCP 3.0 Gen5 x16 slots
- Dual 3000W 80 PLUS Titanium redundant power supply

## Application

High-Performance Computing, High Converged Server

## Specification

<b>Dimensions</b>	2U 4-Node - Rear access (W438 x H87.5 x D840 mm)	<b>Internal I/O</b>	Per node: 1 x TPM header, 1 x VROC connector
<b>Motherboard</b>	MS63-HD1	<b>Backplane Board</b>	Speed & bandwidth: PCIe Gen5 x4 or SATA 6Gb/s or SAS-4 24Gb/s
<b>CPU</b>	5th/4th Gen Intel® Xeon® Scalable Processors\ Dual processors per node, TDP up to 270W Supports TDP up to 350W with no support on OCP slot at ambient 35°C. Supports TDP up to 350W at ambient 30°C.	<b>Security Modules</b>	1 x TPM header with SPI interface per node - Optional TPM2.0 kit: CTM010
<b>Socket</b>	2 x LGA 4677 per node (Socket E)	<b>Power Supply</b>	Dual 3000W 80 PLUS Titanium redundant power supply AC Input: 100-240V Available for 2+1 redundant PSU configuration (optional) *The system power supply requires C19 power cord.
<b>Chipset</b>	Intel® C741 Chipset	<b>System Management</b>	ASPEED® AST2600 management controller GIGABYTE Management Console (AMI MegaRAC SP-X)
<b>Memory</b>	Total 64 x DIMM slots (16 x DIMM slots per node) 8-Channel DDR5 memory architecture RDIMM up to 96GB supported; 3DS RDIMM up to 256GB supported 5th Gen Intel® Xeon®: Up to 5600 MT/s 4th Gen Intel® Xeon®: Up to 4800 MT/s	<b>System Fans</b>	4 x 80x80x80mm (16,500rpm)
<b>LAN</b>	4 x 10/100/1000 Mbps Management LAN 1 x CMC port (Please refer to optional parts for ring topology support)	<b>Operating Properties</b>	Operating temperature: 10°C to 35°C Operating humidity: 8%-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
<b>Video</b>	ASPEED® AST2600 Integrated 2D Graphic Adapter Management chip on CMC board: ASPEED® AST2520A2-GP	<b>Packaging Content</b>	1 x H263-S67-AAW1, 8 x CPU heatsinks, 24 x Carriers, 1 x 3-Section Rail kit
<b>Storage</b>	Total 8 x 2.5" Gen5 NVMe/SATA/SAS-4* hot-swappable bays *SAS card is required for SAS devices support	<b>Part Numbers</b>	Barebone package: 6NH263S67DR000ABW1* - 3-Section Rail kit: 25HB2-A66125-K0R - CPU heatsink: 25ST1-453207-C1R/25ST1-453208-C1R - Power supply: 25EP0-230009-L0S - C19 power cord 125V/15A (US): 25CP1-018000-Q0R (optional) - C19 power cord 250V/16A (EU): 25CP3-01830H-Q0R (optional) - C19 power cord 125V/15A (JP): 25CPA-01830B-Q0R (optional) - M.2 riser card - CMTP061: 9CMTPO61NR-00 (optional) - Riser card - CRSH310: 9CRSH310NR-00 (optional) - Ring topology kit: 6NH263S62S1000AAN11 (optional) - RMA packaging: 6NH263S67SR-RMA-A100 (optional)
<b>RAID</b>	Intel® SATA RAID 0/1/10/5		
<b>Expansion Slots</b>	4 x LP PCIe Gen5 x16 slots 4 x OCP 3.0 Gen5 x16 slots (supports NCSI function)  Optional 4 x LP PCIe Gen5 x16 slots (CRSH310) Optional 4 x M.2 slots (CMTP060): M-key, PCIe Gen4 x4, 2280/22110		
<b>Rear I/O</b>	Total: 8 x USB 3.2 Gen1, 4 x VGA, 4 x MLAN, 1 x CMC		



Learn more about GIGABYTE server at <https://www.gigabyte.com/Enterprise>

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